

Inclined Rotary Plasma Enhanced Chemical Vapor Deposition Pecvd Equipment Tube Furnace Machine

Item Number: KT-PED



Introduction

Upgrade your coating process with PECVD coating equipment. Ideal for LED, power semiconductors, MEMS and more. Deposits high-quality solid films at low temps.

[Learn More](#)

Sample holder	Size	1-6 inches
	Rotate speed	0-20rpm adjustable
	Heating temperature	≤800°C
	Control accuracy	±0.5°C SHIMADEN PID Controller
Gas purge	Flow meter	MASS FLOWMETER CONTROLLER (MFC)
	Channels	4 channels
	Cooling method	Circulating water cooling
Vacuum chamber	Chamber size	Φ500mm X 550mm
	Observation port	Full view port with baffle
	Chamber material	316 Stainless steel
	Door type	Front open type door
	Cap material	304 Stainless steel
	Vacuum pump port	CF200 flange
	Gas inlet port	φ6 VCR connector
	Plasma power	Source power
Plasma power	Coupling mode	Inductively coupled or plate capacitive
	Output power	500W—1000W
	Bias power	500v
	Vacuum pump	Pre- pump
Turbo pump port		CF150/CF200 620L/S-1600L/S
Relief port		KF25
Pump speed		Vane pump:15L/s□ Turbo pump:1200l/s□ 1600l/s
Vacuum degree		≤5×10-5Pa
Vacuum sensor		Ionization/resistance vacuum gauge/film gauge
System	Electric power supply	AC 220V /380 50Hz

Rated power	5kW
Dimensions	900mm X 820mm X870mm
Weight	200kg